

	Application No.	Applicant(s)
Notice of Allowability	10/710,669 Examiner	WENG, YI-TANG Art Unit
	David Nhu	2818
The MAILING DATE of this communication apper All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RI of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this ap or other appropriate communication GHTS. This application is subject t	oplication. If not included n will be mailed in due course. THIS
1. This communication is responsive to 7/28/04.		
2. The allowed claim(s) is/are <u>1-12</u> .		
3. The drawings filed on 28 July 2004 are accepted by the Ex	aminer.	
 4. Acknowledgment is made of a claim for foreign priority una) All b) Some* c) None of the: 1. Certified copies of the priority documents have 2. Certified copies of the priority documents have 3. Opies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONM THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. A SUBSTITUTE OATH OR DECLARATION must be subministrory in the subministrory of the priority of the Notice of Draftspers 1) Pereto or 2) To Paper No./Mail Date (b) including changes required by the Notice of Draftspers 1) Paper No./Mail Date (b) Including changes required by the attached Examiner's Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR 1. each sheet. Replacement sheet(s) should be labeled as such in tile. 7. DEPOSIT OF and/or INFORMATION about the depose attached Examiner's comment regarding REQUIREMENT in the summer of t	been received. been received in Application No cuments have been received in this of this communication to file a reply ENT of this application. itted. Note the attached EXAMINER es reason(s) why the oath or declarate t be submitted. on's Patent Drawing Review (PTO a Amendment / Comment or in the Comment or in the Comment of BIOLOGICAL MATERIAL in itted to for BIOLOGICAL MATERIAL in comment of BIOLOGICAL MATERIAL in comment or in the drawing to BIOLOGICAL MATERIAL in comment or in the comment of BIOLOGICAL MATERIAL in comment or in the comment of BIOLOGICAL MATERIAL in comment or in the comment of BIOLOGICAL MATERIAL in comment or in the comment of BIOLOGICAL MATERIAL in comment or in the comment of BIOLOGICAL MATERIAL in comment or in the comment or in the comment or in the comment or in the comment of BIOLOGICAL MATERIAL in comment or in the com	national stage application from the complying with the requirements R'S AMENDMENT or NOTICE OF ation is deficient. -948) attached Office action of ings in the front (not the back) of (d). must be submitted. Note the
 Attachment(s) 1. Notice of References Cited (PTO-892) 2. Notice of Draftperson's Patent Drawing Review (PTO-948) 3. Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 01 4. Examiner's Comment Regarding Requirement for Deposit of Biological Material 	6. Interview Summary Paper No./Mail Da 8), 7. Examiner's Amend 8. Examiner's Statem 9. Other	ite

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REASONS FOR ALLOWANCE

1. Claims 1-12 are allowed.

2. The following is an examiner's statement of reasons for allowance: None of the references of record teaches or suggests as cited in claims 1, 7: electroplating copper in said recessed trench area to form said copper circuit pattern including a to-be-Au (gold)-plating area that has a larger surface area as the terminal of said copper circuit pattern; stripping said first patterned photoresist layer; forming a second patterned photoresist layer exposing said to-be-Au-plating area of said copper circuit pattern; using said second patterned photoresist layer as an etching hard mask, etching away said thin copper base layer exposed by said second patterned photoresist layer and said to-be-Au-plating area; forming a third patterned photoresist layer on said second patterned photoresist layer to mend a recess under said second patterned photoresist layer; using said third patterned photorsist layer as an electroplating mask, electroplating a metal layer onto said copper circuit pattern in said to-be-Au-plating area; stripping said second and third patterned photoresist layers; and etching away remaining said thin copper base layer being exposed after stripping said second and third patterned photoresist layers (as cited in claim 1); ; forming a second patterned photoresist layer exposing said to-be-Au-plating area of said copper circuit pattern; using said second patterned photoresist layer as an etching hard mask, etching away said thin copper base layer exposed by said second patterned photoresist layer and said to-be-Au-plating area; stripping said second patterned photoresist layer; forming a third patterned photoresist layer on said on said carrier plate to expose said to-be-Au-plating area of said copper circuit pattern; using said third patterned photoresist layer as an electroplating mask, electroplating a metal layer onto said

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to-be-Au-plating area; stripping said third photoresist layer; and etching away remaining said copper seed layer being exposed after stripping said third patterned photoresist layer (as cited

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copper seed layer being expected after emphing data thing patterned printerest tayer (as effect

in claim 7);

5. Any comments considered necessary by applicant must be submitted no later than the

payment of the issue fee and, to avoid processing delays, should preferably accompany the

issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons

for Allowance."

CONCLUSION

6. The prior art made of record and not relied upon is considered pertinent to applicant's

disclosure: Hsu et al (6,576,540 B2): Method for Fabricating Substrate within a NI/Au

Structure Electroplated on Electrical Contact Pads.

7. Any inquiry concerning this communication on earlier communications from the examiner

should be directed to David Nhu, (571)272-1792. The examiner can normally be reached

on Monday-Friday from 7:30 AM to 5:00 PM.

The examiner's supervisor, David Nelms can be reached on (571)272-1787.

The fax phone number for the organization where this application or proceeding is assigned is

(703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should

be directed to the receptionist whose telephone number is (703) 308-0956

David Nhu

Da/

April 5, 2005

DAVID NHU